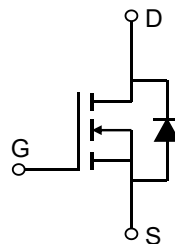


Description

Features

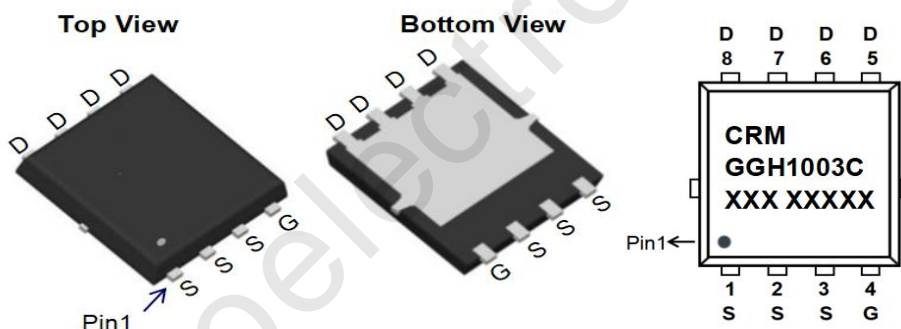
- 100V, 138A
 $R_{DS(ON)}$ Typ = 3mΩ @ $V_{GS} = 10V$
- Advanced Split Gate Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔV_{ds} TESTED!



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMGGH1003C	CRMGGH1003C	PDFN5x6-8L	TAPING	13"	5000	60000

Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units	
V _{DS}	Drain-to-Source Voltage	100	V	
V _{GS}	Gate-to-Source Voltage	±20	V	
I _D	Continuous Drain Current	T _C = 25°C	138	A
		T _C = 100°C	82.8	A
I _{DM}	Pulsed Drain Current ⁽¹⁾	552	A	
E _{AS}	Single Pulsed Avalanche Energy ⁽²⁾	342	mJ	
P _D	Power Dissipation	T _C = 25°C	139	W
R _{θJC}	Thermal Resistance, Junction to Case	0.9	°C/W	
T _J , T _{STG}	Junction & Storage Temperature Range	-55 to 150	°C	

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	100	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 100V, V _{GS} = 0V	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	2.4	2.7	3.6	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = 10V, I _D = 30A	-	3	3.9	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 50V, f = 1MHz	-	3658	-	pF
C _{oss}	Output Capacitance		-	1536	-	pF
C _{rss}	Reverse Transfer Capacitance		-	19	-	pF
Q _g	Total Gate Charge	V _{GS} = 0 to 10V V _{DS} = 50V, I _D = 20A	-	49	-	nC
Q _{gs}	Gate Source Charge		-	17	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	6	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime	V _{GS} = 10V, V _{DD} = 50V I _D = 48A, R _{GEN} = 6Ω	-	26	-	ns
t _r	Turn-On Rise Time		-	15	-	ns
t _{d(off)}	Turn-Off DelayTime		-	28	-	ns
t _f	Turn-Off Fall Time		-	12	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	138	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	552	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = 30A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I _F = 24A, di/dt = 100A/us	-	60	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	70	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting $T_J = 25^\circ\text{C}$, $V_{DD} = 50\text{V}$, $V_G = 10\text{V}$, $R_G = 25\text{ohm}$, $L = 0.5\text{mH}$, $I_{AS} = 37\text{A}$
 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Test Circuit

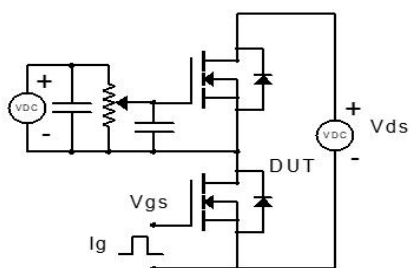


Figure 1: Gate Charge Test Circuit & Waveform

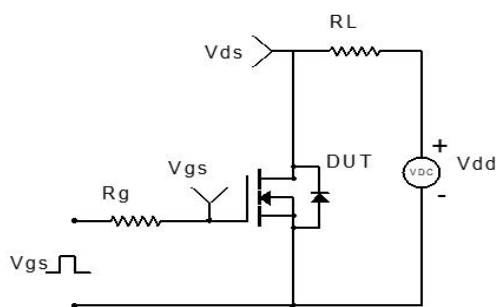


Figure 2: Resistive Switching Test Circuit & Waveform

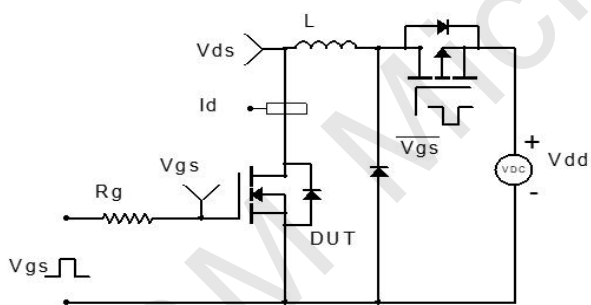


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

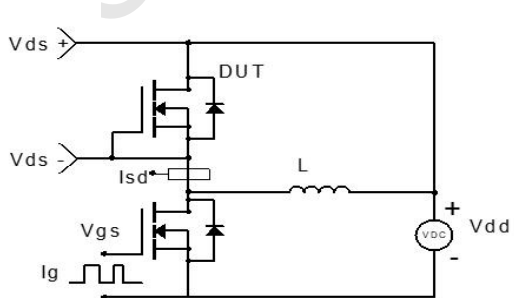
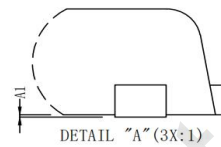
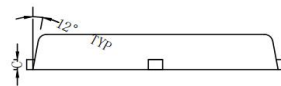
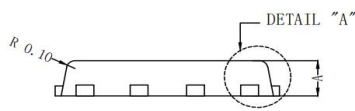
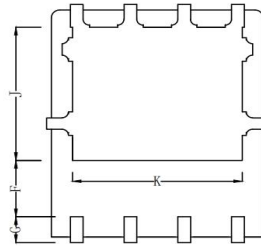
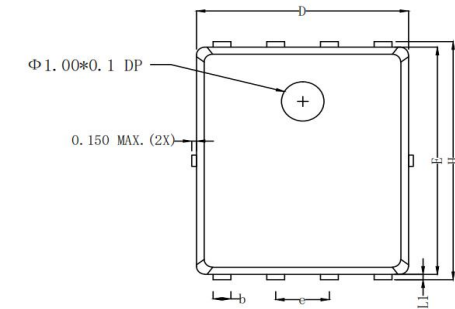


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(PDFN5x6-8L)




Dimensions In Millimeterer			
Symbol	MIN	TYP	MAX
A	0.90	1.00	1.10
A1	0.00	0.03	0.05
b	0.25	0.30	0.35
c	0.254 REF		
D	4.80	4.90	5.00
F	1.35 REF		
E	5.65	5.75	5.85
e	1.27 BSC		
H	5.90	6.00	6.10
L1	0.10	0.13	0.16
G	0.55 REF		
K	4.00 REF		
J	3.45 REF		

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